

71. The method of claim 63 wherein said insulating, separating layer comprises the polymer benzocyclobutene (BCB).

72. The method of claim 63 wherein said insulating, separating layer is of a thickness after curing within the range of approximately 1.0 to 30 um.

73. The method of claim 63 wherein said insulating, separating layer is spin-on coated and cured.

74. The method of claim 63 wherein said openings have an aspect ratio within the range of approximately 1 to 10.

75. The method of claim 63 wherein said metal contacts is selected from the group comprising sputtered aluminum, CVD tungsten, CVD copper, electroplated copper, electroless nickel and damascene metal filling.

76. The method of claim 63 wherein said openings through said insulating, separating layer have sloped sides and wherein each of said openings is wider at its top.

77. The method of claim 63 thereby furthermore functionally and physically extending said top metalization system connected to

said overlaying interconnecting metalization structure, wherein
 said top metalization system comprises a plurality of ground
 planes, in one or more layers, wherein furthermore said
 overlaying interconnecting metalization structure directly
 interconnects a multiplicity of ground wires said ground wires to
 be connected with fine-wire ground wires thereby functionally
 extending or connecting said fine-wire ground wire metal
 interconnects with said wide-wire metal ground wire interconnects
 contained within said top metalization system thereby extending
 the fine-wire ground wires as contained within the overlaying
 interconnecting metalization structure with said top metalization
 system.

78. The method of claim 63 thereby furthermore functionally and physically extending said top metalization system connected to said overlaying interconnecting metalization structure, wherein said top metalization system comprises a plurality of signal planes, in one or more layers, wherein furthermore said overlaying interconnecting metalization structure directly interconnects a multiplicity of signal wires said signal wires to be connected with fine-wire signal wires thereby functionally extending or connecting said fine-wire signal wire metal interconnects with said wide-wire metal signal wire interconnects contained within said top metalization system thereby extending

the fine-wire signal wires as contained within the overlaying interconnecting metalization structure with said top metalization system.

79. The method of claim 63 thereby furthermore functionally and physically extending said top metalization system connected to said overlaying interconnecting metalization structure, wherein said top metalization system comprises a plurality of power planes, in one or more layers, wherein furthermore said overlaying interconnecting metalization structure directly interconnects a multiplicity of power wires said power wires to be connected with fine-wire power wires thereby functionally extending or connecting said fine-wire power wire metal interconnects with said wide-wire metal power wire interconnects contained within said top metalization system thereby extending the fine-wire power wires as contained within the overlaying interconnecting metalization structure with said top metalization system.